General Description

The SJD40N042 uses advanced trench technology to provide excellent R_{DS(ON)}, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a wide variety of applications.

Features

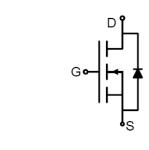
- Low Gate Charge
- 100% UIS Tested, 100% DVDS Tested
- High Power and current handing capability
- Lead free product is acquired

Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

Key Performance Parametes

Parameter	Value	Unit
V _{DS}	40	V
R _{DS(ON)_TYP}	3.9	mΩ
I _D	90	Α
Q _G	72	nC







Schematic Diagram

TO-252(DPAK) top view

Package Marking and Ordering Information

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJD40N042	SJD40N042	TO-252	Tape	\	\	2500 Pcs

Table 1. Absolute Maximum Ratings (T_C=25℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit	
V _{DS}	Drain-Source Voltage (V _{GS} =0V)	40	V	
V _{GS}	Gate-Source Voltage (V _{DS} =0V)	±20	V	
1-	Drain Current-Continuous(Tc=25℃)		А	
ID	I _D Drain Current-Continuous(T _C =100°C)		А	
I _{DM} (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	360	А	
D-	PD Maximum Power Dissipation(T _C =25°C) Maximum Power Dissipation(T _C =100°C)		W	
PD			W	
E _{AS}	Avalanche energy (Note 2)	324	mJ	
TJ, TSTG	Operating Junction and Storage Temperature Range	-55 To 150	С	

Table 2. Thermal Characteristic

Symbol	Parameter	Тур	Max	Unit
R _θ JC	Thermal Resistance, Junction-to-Case		1.8	°C/W



Table 3. Electrical Characteristics (T_J=25℃ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
On/Off States						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =250μA	40			V
	7 0 1 1/1 5 1 0 1	V _{DS} =40V, V _{GS} =0V T _J =25°C			1	μΑ
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =40V, V _{GS} =0V T _J =125℃			100	μΑ
Igss	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250µA	1		2.5	V
g FS	Forward Transconductance	V _{DS} =5V, I _D =20A		25		S
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =10V, I _D =20A T _J =25°C		3.9	5.1	mΩ
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =4.5V, I _D =20A T _J =25°C		5	6.6	mΩ
Dynamic Chara	acteristics		•	•		•
Ciss	Input Capacitance			3763		pF
Coss	Output Capacitance	V _{DS} =20V,V _{GS} =0V, f=1.0MHz		265		pF
Crss	Reverse Transfer Capacitance			222		pF
Rg	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1.0MHz		1.6		Ω
Switching Para	meters		•	•		•
t _{d(on)}	Turn-on Delay Time			18.8		nS
t _r	Turn-on Rise Time	V_{GS} =10V, V_{DS} =20V, R_L =1 Ω , R_{GEN} =6 Ω		54.4		nS
t _{d(off)}	Turn-Off Delay Time			62		nS
t _f	Turn-Off Fall Time			11.6		nS
Qg	Total Gate Charge			72		nC
Q_{gs}	Gate-Source Charge	V _{GS} =10V, V _{DS} =20V, I _D =20A		8.6		nC
Q_{gd}	Gate-Drain Charge			16		nC
Source-Drain D	Piode Characteristics	•		•		•
I _{SD}	Source-Drain Current (Body Diode)				90	Α
V _{SD}	Forward on Voltage (Note 3)	V _{GS} =0V, I _S =20A			1.2	V
t _{rr}	Reverse Recovery Time	I _F =20A, dI/dt=100A/μs		21.8		ns
Qrr	Reverse Recovery Charge	Ir=20A, dI/dt=100A/μs		13.4		nC

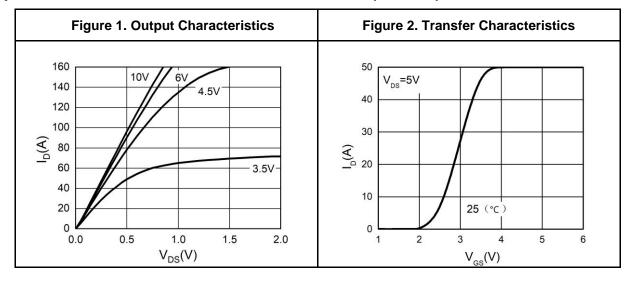
Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

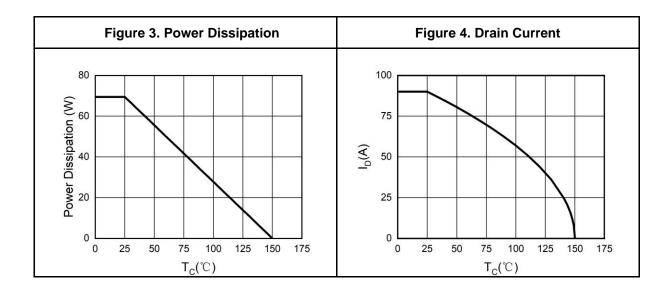
Notes 2.E_{AS} condition: $T_J=25^{\circ}C$, $V_{DD}=40V$, $V_G=10V$, $Rg=25\Omega$, L=0.5mH.

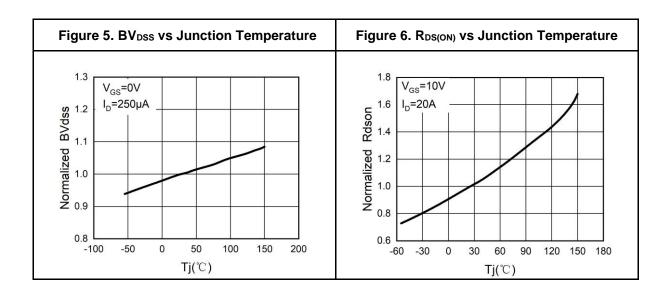
Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.



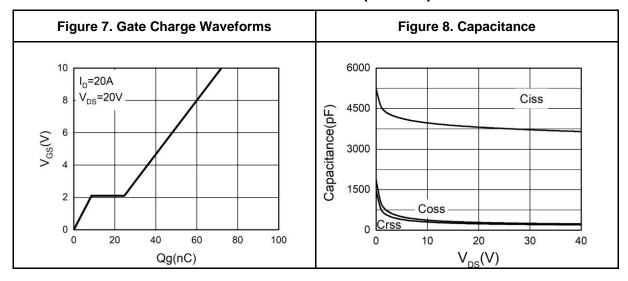
Typical Electrical And Thermal Characteristics (Curves)

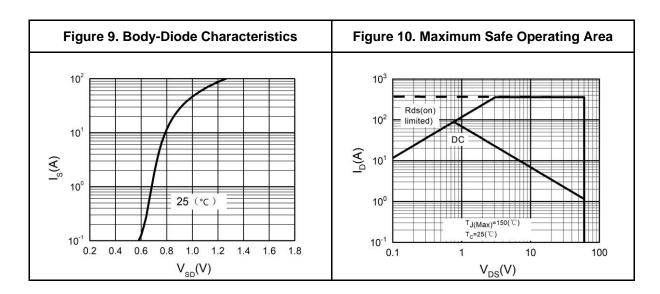






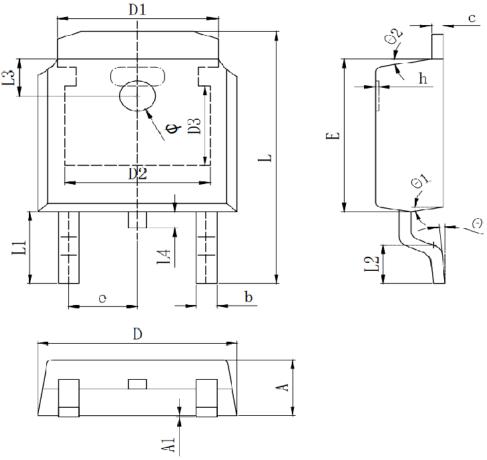
Typical Electrical And Thermal Characteristics (Curves)







TO-252 Package Information



Symbol	Dimensions In Millimeters			
Symbol	Min.	Тур.	Max.	
А	2.200	2.300	2.400	
A1	0.000		0.127	
b	0.640	0.690	0.740	
c(电镀后)	0.460	0.520	0.580	
D	6.500	6.600	6.700	
D1		5.334 REF		
D2		4.826 REF		
D3	3.166 REF			
E	6.000	6.100	6.200	
е		2.286 TYP		
h	0.000	0.100	0.200	
L	9.900	10.100	10.300	
L1	2.888 REF			
L2	1.400	1.550	1.700	
L3		1.600 REF		
L4	0.600	0.800	1.000	
Ф	1.100	1.200	1.300	
θ	0°		8°	
θ1	9° TYP			
θ2	9° TYP			

Attention

This product described in this document can not be used in life support devices or systems, aircraft's control systems, and other applications whose failure can be reasonably expected to result in serious physical and/or material damage, apart from that when an application agreement is signed between customer and Wuxi Shangjia Semiconductor.

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